

**GENERAL DESCRIPTION**

All devices utilize the most advanced design and process technologies. These features provide the most consistent and reliable chip and package combination designed, built and tested specifically for use in airborne DME.

- \* Gold thin-film metallization -- proven highest Mean Time to Failure.
- \* Surface passivation -- eliminates contamination and extends life.
- \* Eutectic die attach -- reduces junction temperature and extends MTTF.
- \* Gold controlled-loop wire bonding -- consistent RF performance.
- \* Low thermal-resistance packages -- reduce junction temperature and extend life.

**ABSOLUTE MAXIMUM RATINGS**

Maximum Power Dissipation @ 25°C Case Temperature 1700 W

**Maximum Voltage and Current**

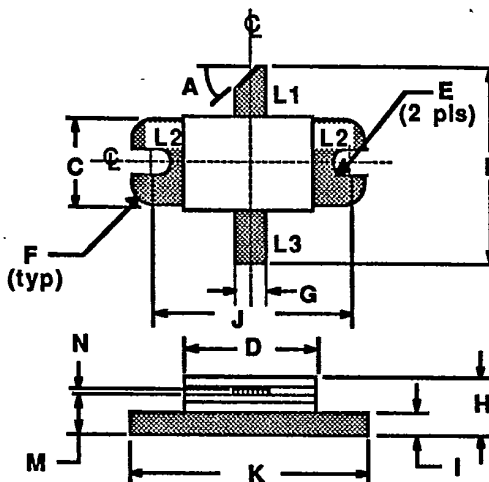
BVces Collector to Emitter Voltage 55 V  
 BVebo Emitter to Base Voltage 3.5 V  
 Ic Collector Current 40 A

**Maximum Temperatures**

Storage Temperature -65 to +200 °C  
 Operating Junction Temperature +200 °C

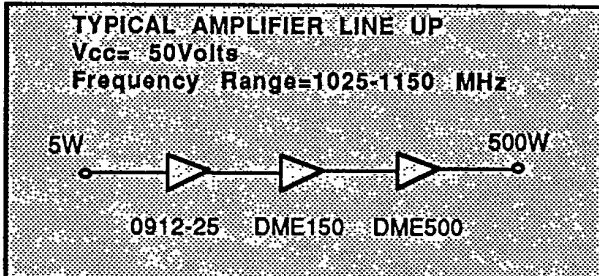
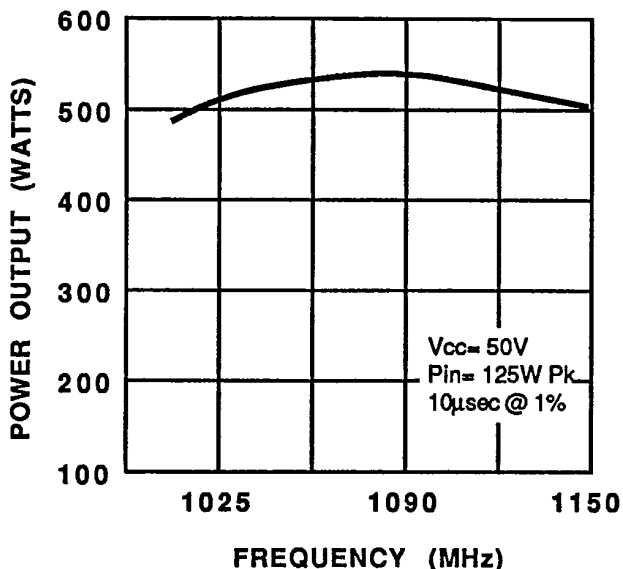
**DME 500**  
 500 WATTS - 50 VOLTS  
 1025/1150 MHz

**AVIONICS**



DIM	Millimeter	TOL	Inches	TOL
L1:C	45 °	5 °	45 °	5 °
L2:B	20.32	.76	.800	.030
L3:E	9.78	.13	.385	.005
A	12.70	.13	.500	.005
B	1.52 R	.13	.060 R	.005
C	1.52 R	.13	.060 R	.005
D	3.81	.13	.150	.005
E	5.21	REF	.205	REF
F	1.52	.13	.060	.005
G	17.78	.13	.700	.005
H	22.86	.13	.900	.005
I	3.05	.13	.120	.010
J	0.13	.02	.005	.001
K				
M				
N				

**(TYPICAL) POWER OUTPUT**



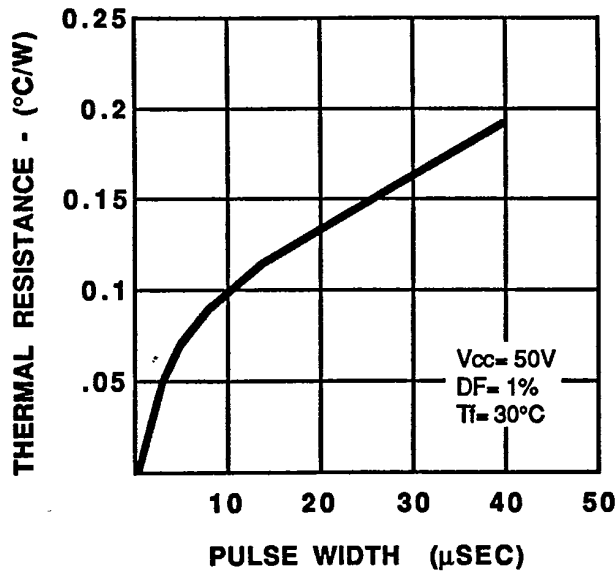
**DME 500-2**

**ELECTRICAL CHARACTERISTICS<sup>1</sup>**

SYMBOL	CHARACTERISTICS	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
P <sub>out</sub>	Power Output	f= 1025 to 1150 MHz V <sub>cc</sub> = 50V Pulse Width = 10 μsec @ 1%	500			Watts
P <sub>in</sub> <sup>2</sup>	Power Input				125	Watts
P <sub>g</sub>	Power Gain			6.0		dB
η <sub>c</sub>	Collector Efficiency				35	%
VSWR	Load Mismatch Tolerance				10:1	
BV <sub>ebo</sub>	Breakdown Voltage (Emitter to Base)	I <sub>c</sub> = 0A, I <sub>e</sub> =30mA	3.5			Volts
BV <sub>ces</sub>	Breakdown Voltage (Collector to Emitter)	V <sub>be</sub> = 0A, I <sub>c</sub> = 40mA	55			Volts
h <sub>fe</sub>	DC-Current Gain	V <sub>ce</sub> = 5V, I <sub>c</sub> = 500mA	10		100	
θ <sub>jc</sub>	Thermal Resistance				0.1	°C/W

Note 1: T<sub>c</sub> = +25°C unless otherwise specified  
 Note 2: Pulse width 10μsec @ 1% duty

**THERMAL RESISTANCE VS PULSE WIDTH**

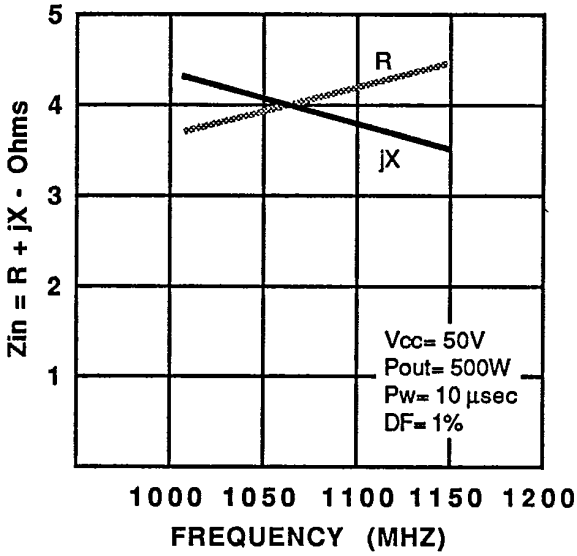


SPECIFICATIONS MAY BE SUBJECT TO CHANGE WITHOUT NOTICE

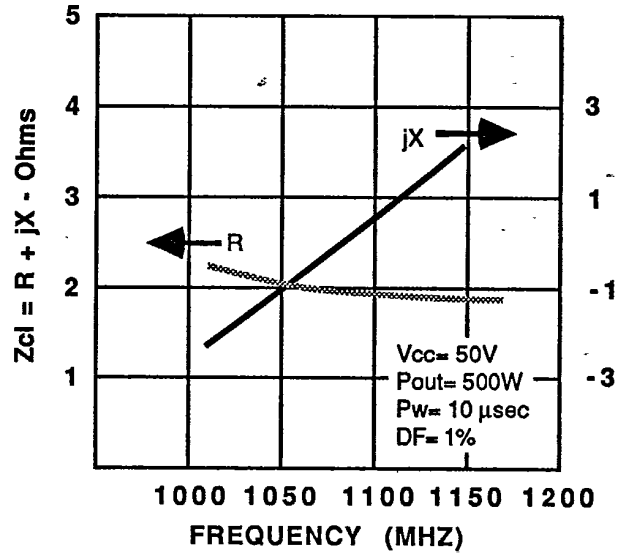
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**DME 500-3**

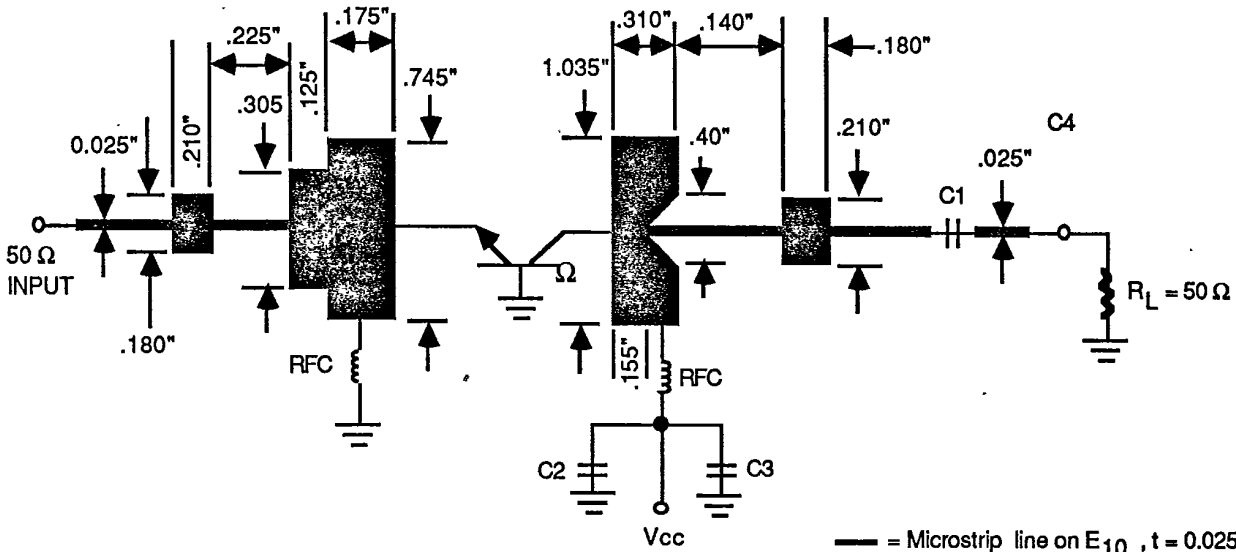
**SERIES INPUT IMPEDANCE VS FREQUENCY (TYPICAL)**



**SERIES LOAD IMPEDANCE VS FREQUENCY (TYPICAL)**



**1025/1150 MHz TEST AMPLIFIER**



— = Microstrip line on E10, t = 0.025"  
 C1, C2 = 82 PF chip capacitor  
 C3 = 500μ FDC 75V capacitor

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